

G4L3-ZD1-LAX3

HPC/AI Server - 4U DP NVIDIA HGX™ H200 DLC



Key Features

- Liquid-cooled NVIDIA HGX™ H200
- CPU+GPU direct liquid cooling solution with leak detection
- 900GB/s GPU-to-GPU bandwidth with NVIDIA NVLink™ and NVSwitch™
- Dual AMD EPYC™ 9005/9004 Series Processors
- 12-Channel DDR5 RDIMM, 24 x DIMMs
- Dual ROM Architecture
- Compatible with NVIDIA® BlueField®-3 DPUs and NVIDIA ConnectX®-7 NICs
- 2 x 10Gb/s LAN ports via Intel® X710-AT2
- 2 x M.2 slots with PCIe Gen3 x4 and x1 interface
- 8 x 2.5" Gen5 NVMe hot-swap bays
- 4 x FHHL dual-slot PCIe Gen5 x16 slots
- 8 x FHHL single-slot PCIe Gen5 x16 slots
- 4+4 3000W 80 PLUS Titanium redundant power supplies

Applications

AI Platform, AI Training Server, AI Inference Server, High-Performance Computing Server...

Specification

Dimensions	4U (W447 x H175.3 x D920 mm)	Modular GPU	Liquid-cooled NVIDIA HGX™ H200 with 8 x SXM GPUs
Motherboard	MZB3-PE0	PCIe Expansion Slots	4 x FHHL dual-slot PCIe Gen5 x16 8 x FHHL single-slot PCIe Gen5 x16
CPU	AMD EPYC™ 9005/9004 Series Processors Dual processor, cTDP up to 500W	I/O Ports	Front: 2 x USB 3.2 Gen1, 1 x VGA, 2 x RJ45, 1 x MLAN (default) Rear: 1 x MLAN
OS Compatibility	OS Support List	Backplane Board	PCIe Gen5 x4
Socket	2 x LGA 6096 (Socket SP5)	TPM	1 x TPM header (SPI), Optional TPM2.0 kit: CTM012
Chipset	System on Chip	Power Supply	4+4 3000W 80 PLUS Titanium redundant power supplies AC Input: 115-240V *The system power supply requires C19 power cord.
Memory	12-Channel DDR5 RDIMM, 24 x DIMMs [EPYC 9005] Up to 6400 MT/s [EPYC 9004] Up to 4800 MT/s	System Management	ASPEED® AST2600 Baseboard Management Controller GIGABYTE Management Console web interface
LAN	Front: 2 x 10Gb/s LAN (1 x Intel® X710-AT2), Support NCSI 1 x 10/100/1000 Mbps Management LAN Rear: 1 x 10/100/1000 Mbps Management LAN	System Fans	Motherboard: 2 x 60x60x56mm / 2 x 60x60x76mm PCIe slots: 4 x 80x80x56mm GPU tray: 4 x 60x60x38mm
Video	Integrated in ASPEED® AST2600 - 1 x VGA port	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
Storage	Front hot-swap: 8 x 2.5" Gen5 NVMe Internal M.2: 1 x M.2 (2280/22110), PCIe Gen3 x4 1 x M.2 (2280/22110), PCIe Gen3 x1	Packaging Content	1 x G4L3-ZD1-LAX3 1 x L-shape Rail kit
RAID	N/A	Ordering Part Numbers	6NG4L3ZD1DR000LCX3*



Learn more at: <https://www.gigabyte.com/Enterprise>

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